

U.S.S.N. 09/976,082

In The Drawings

Figures 1 and 2 have been amended and a redline copy of the drawing changes are hereby submitted for the Examiner's approval.

In The Specification

Paragraph 004 has been amended as follows:

004 In a typical sputter chamber, the major components utilized include a stainless steel chamber that is vacuum-tight and is equipped with a helium leak detector, a pump that has the capacity to reduce the chamber pressure to at least  $10^{-6}$  torr or below, various pressure gauges, a sputter source or target, a RF or DC power supply, a wafer holder, a chamber shield and a clamp ring. The sputter source is normally mounted on the roof of the chamber such that it faces a wafer holder positioned in the center of the chamber facing each other. The sputter source utilized can be a W or TiW disc for a process in which W or TiW is sputtered. A typical sputter chamber is that supplied by the Applied Materials, Inc. of Santa Clara, CA. under the trade name